23.(Amended) An electronic component mounting apparatus as claimed in claim 10, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler (6f) with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.

24.(Amended) An electronic component unit as claimed in claim 18, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler (6f) with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.

27.(Amended) An electronic component mounting method as claimed in claim 25, wherein

the insulating resin (306m) is an insulative thermosetting epoxy resin, and an amount of the inorganic filler mixed with this insulative thermosetting epoxy resin is 5 to 90 wt% of the insulative thermosetting epoxy resin.

29.(Amended) An electronic component mounting method as claimed in claim 25, wherein the electronic component (1) has a plurality of electrodes (2), a solid insulating resin sheet (6) that has a configurational dimension smaller than an outline dimension (OL) defined by joining the plurality of electrodes (2) of the electronic component (1) is stuck as the insulating resin layer to the circuit board (4) before the positional alignment and

thereafter subjected to the positional alignment, and at the bonding time, the insulating resin interposed between the electronic component and the circuit board is hardened while concurrently correcting the warp of the circuit board by pressurizing the electronic component against the circuit board with heat applied to the insulating resin sheet (6), so that the electronic component is bonded to the circuit board.

30.(Amended) An electronic component mounting method as claimed in claim 25, wherein the gold bump that has an approximately conically shaped tip is formed on the electrode of the electronic component by means of the capillary that has a chamfer angle (θc) of not greater than 100° when a gold ball (96a) is formed by an electric spark at a tip of a gold wire (95) similarly to the wire bonding in forming the bump on the electronic component and a tip shape provided with no flat portion to be brought in contact with the gold ball.

36.(Amended) An electronic component mounting method as claimed in claim 25, wherein the inorganic filler mixed with the insulating resin is provided by a plurality of types of inorganic fillers (6f-1, 6f-2), which have different mean particle diameters.

37.(Amended) An electronic component mounting method as claimed in claim 25, wherein the insulating resin layer (6, 306b) has a portion brought in contact with either

the electronic component or the board, the portion having a smaller amount of inorganic filler than that of the other portion.

39.(Amended) An electronic component mounting method as claimed in claim 37, wherein the portion brought in contact with the electronic component is provided by an insulating resin that improves adhesion to a film material used on a surface of the electronic component, and the portion brought in contact with the board is provided by an insulating resin that improves adhesion to a material used on a surface of the board.

40.(Amended) An electronic component mounting method as claimed in claim 25, wherein the insulating resin layer (6, 306b) has a portion brought in contact with either the electronic component or the board, the portion being mixed with no inorganic filler.

43.(Amended) An electronic component mounting method as claimed in claim 5, wherein heating is effected from the upper surface side of the electronic component or from the board side or from both the electronic component side and the board side when metallically bonding the gold bump to the electrode of the board with supersonic waves applied.